

L, S-BAND SPDT SWITCH

<R> DESCRIPTION

The μ PG2030TK is a GaAs MMIC for L, S-band SPDT (Single Pole Double Throw) switch which were developed for mobile phone and other L, S-band applications.

This device can operate 2 control switching by control voltage 2.7 to 5.3 V, at frequencies from 0.5 to 2.5 GHz, having the low insertion loss and high isolation.

This device is housed in a 6-pin lead-less minimold package and is suitable for high-density surface mounting.

FEATURES

- <R> • Switch control voltage : $V_{cont}(H) = 2.7$ to 5.3 V (2.8 V TYP.)
: $V_{cont}(L) = -0.2$ to $+0.2$ V (0 V TYP.)
- Low insertion loss : $L_{INS1} = 0.25$ dB TYP. @ $f = 0.5$ to 1.0 GHz, $V_{cont} = 2.8$ V/0 V
: $L_{INS2} = 0.30$ dB TYP. @ $f = 1.0$ to 2.0 GHz, $V_{cont} = 2.8$ V/0 V
: $L_{INS3} = 0.35$ dB TYP. @ $f = 2.0$ to 2.5 GHz, $V_{cont} = 2.8$ V/0 V
- High isolation : $ISL1 = 27$ dB TYP. @ $f = 0.5$ to 2.0 GHz, $V_{cont} = 2.8$ V/0 V
: $ISL2 = 24$ dB TYP. @ $f = 2.0$ to 2.5 GHz, $V_{cont} = 2.8$ V/0 V
- High power : $P_{in}(0.1\text{ dB}) = +27.0$ dBm TYP. @ $f = 2.0$ GHz, $V_{cont} = 2.8$ V/0 V
: $P_{in}(1\text{ dB}) = +30.0$ dBm TYP. @ $f = 2.0$ GHz, $V_{cont} = 2.8$ V/0 V (Reference value)
- High-density surface mounting : 6-pin lead-less minimold package ($1.5 \times 1.1 \times 0.55$ mm)

APPLICATIONS

- PCS, W-LAN, WLL and Bluetooth™ etc.

<R> ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
μ PG2030TK-E2	μ PG2030TK-E2-A	6-pin lead-less minimold (1511 PKG) (Pb-free)	G3R	<ul style="list-style-type: none"> • Embossed tape 8 mm wide • Pin 1, 6 face the perforation side of the tape • Qty 5 kpcs/reel

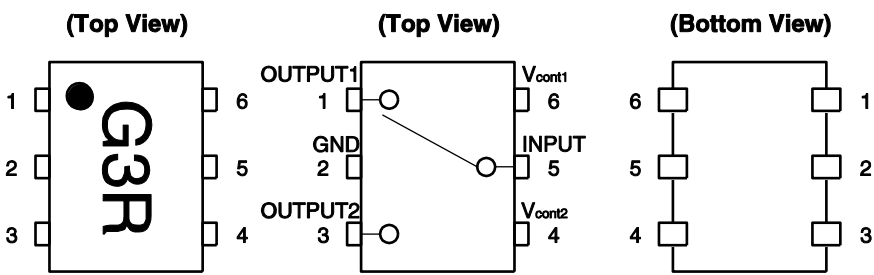
Remark To order evaluation samples, please contact your nearby sales office.

Part number for sample order: μ PG2030TK-A

Caution Although this device is designed to be as robust as possible, ESD (Electrostatic Discharge) can damage this device. This device must be protected at all times from ESD. Static charges may easily produce potentials of several kilovolts on the human body or equipment, which can discharge without detection. Industry-standard ESD precautions must be employed at all times.

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.

<R> PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM



Pin No.	Pin Name
1	OUTPUT1
2	GND
3	OUTPUT2
4	V _{cont2}
5	INPUT
6	V _{cont1}

TRUTH TABLE

V _{cont1}	V _{cont2}	INPUT-OUTPUT1	INPUT-OUTPUT2
Low	High	ON	OFF
High	Low	OFF	ON

ABSOLUTE MAXIMUM RATINGS (T_A = +25°C, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Switch Control Voltage	V _{cont}	6.0 ^{Note}	V
Input Power	P _{in}	+33	dBm
Operating Ambient Temperature	T _A	-45 to +85	°C
Storage Temperature	T _{stg}	-55 to +150	°C

<R> **Note** |V_{cont1} - V_{cont2}| ≤ 6.0 V

RECOMMENDED OPERATING RANGE (T_A = +25°C, unless otherwise specified)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Switch Control Voltage (H)	V _{cont} (H)	2.7	2.8	5.3	V
Switch Control Voltage (L)	V _{cont} (L)	-0.2	0	0.2	V

ELECTRICAL CHARACTERISTICS**(T_A = +25°C, V_{cont} = 2.8 V/0 V, DC cut capacitors = 56 pF, unless otherwise specified)**

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Insertion Loss 1	L _{INS1}	f = 0.5 to 1.0 GHz	–	0.25	0.45	dB
Insertion Loss 2	L _{INS2}	f = 1.0 to 2.0 GHz	–	0.30	0.50	dB
Insertion Loss 3	L _{INS3}	f = 2.0 to 2.5 GHz	–	0.35	0.55	dB
Isolation 1	ISL1	f = 0.5 to 2.0 GHz	23	27	–	dB
Isolation 2	ISL2	f = 2.0 to 2.5 GHz	20	24	–	dB
Input Return Loss	RL _{in}	f = 0.5 to 2.5 GHz	15	20	–	dB
Output Return Loss	RL _{out}	f = 0.5 to 2.5 GHz	15	20	–	dB
0.1 dB Gain Compression	P _{in (0.1 dB)}	f = 2.0 GHz	+25.5	+27.0	–	dBm
Input Power ^{Note}		f = 2.5 GHz	+25.5	+27.0	–	dBm
Switch Control Current	I _{cont}	No signal	–	4	20	μ A
Switch Control Speed	t _{sw}		–	50	500	ns

Note P_{in (0.1 dB)} is measured the input power level when the insertion loss increases more 0.1 dB than that of linear range.

STANDARD CHARACTERISTICS FOR REFERENCE**(T_A = +25°C, V_{cont} = 2.8 V/0 V, DC cut capacitors = 56 pF, unless otherwise specified)**

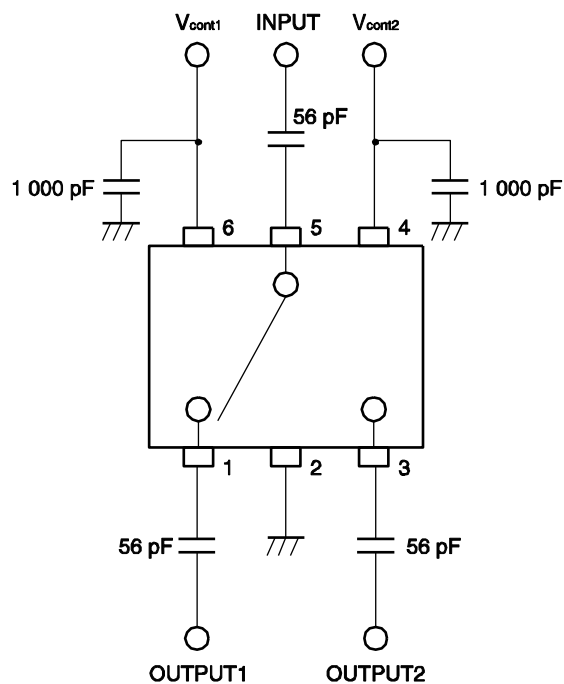
Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
1 dB Gain Compression Input Power ^{Note}	P _{in (1 dB)}	f = 2.0 GHz	–	+30.0	–	dBm

Note P_{in (1 dB)} is measured the input power level when the insertion loss increases more 1 dB than that of linear range.

Caution This device is used it is necessary to use DC cut capacitors.

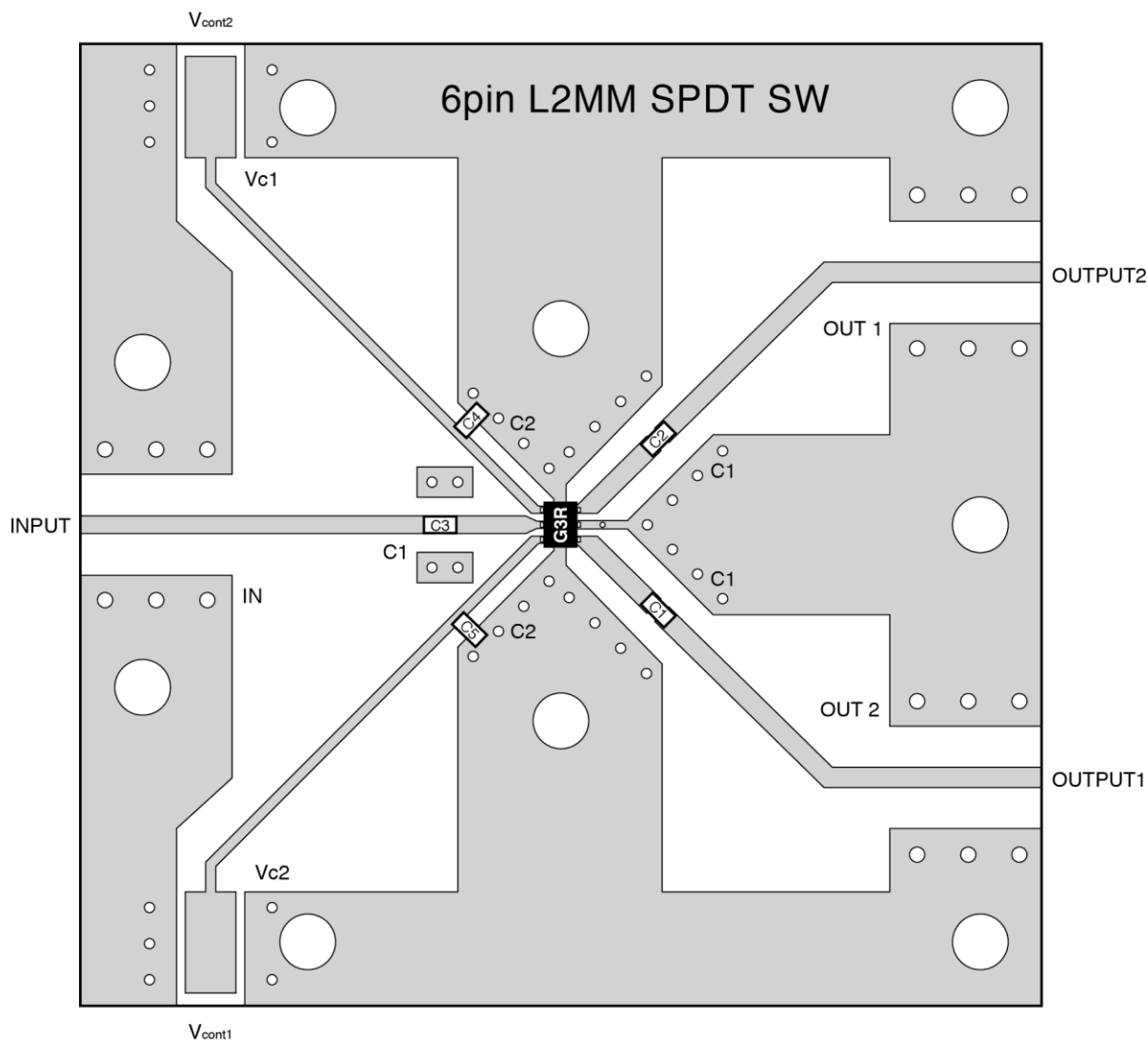
The value of DC cut capacitors should be chosen to accommodate the frequency of operation, bandwidth, switching speed and the condition with actual board of your system. The range of recommended DC cut capacitor value is less than 100 pF.

EVALUATION CIRCUIT ($V_{cont} = 2.8 \text{ V/0 V}$, DC cut capacitors = 56 pF)



The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

ILLUSTRATION OF THE TEST CIRCUIT ASSEMBLED ON EVALUATION BOARD



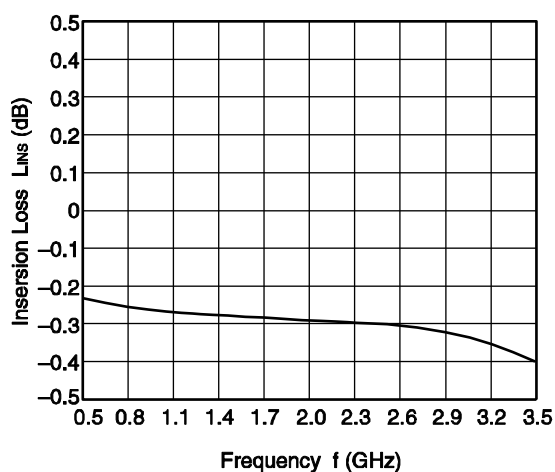
USING THE EVALUATION BOARD

Symbol	Values
C1, C2, C3	56 pF
C4, C5	1 000 pF

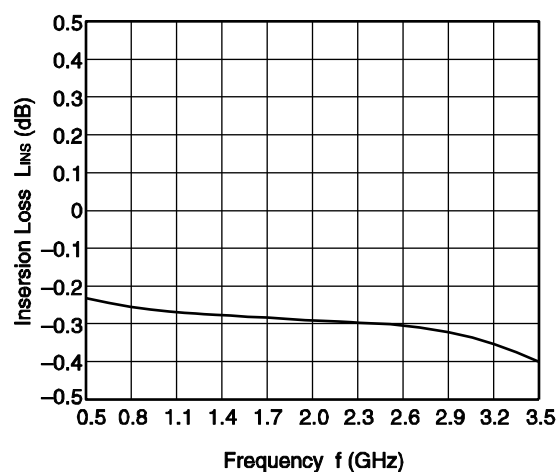
TYPICAL CHARACTERISTICS

($T_A = +25^\circ\text{C}$, $V_{\text{cont}} = 2.8 \text{ V/0 V}$, DC cut capacitors = 56 pF, unless otherwise specified)

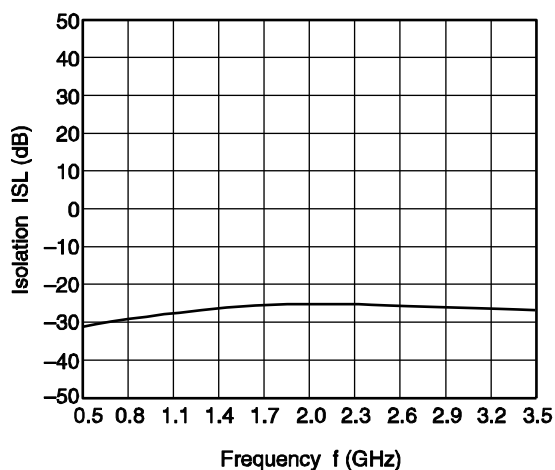
INPUT-OUTPUT1 •
INSERTION LOSS vs. FREQUENCY



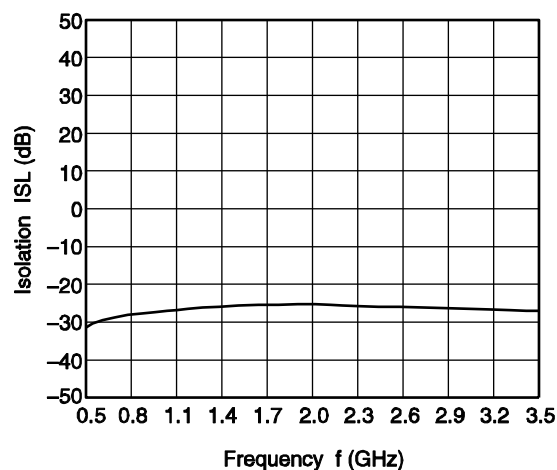
INPUT-OUTPUT2 •
INSERTION LOSS vs. FREQUENCY



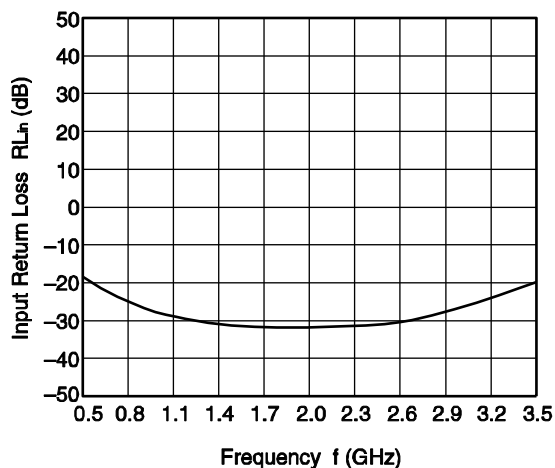
INPUT-OUTPUT1 •
ISOLATION vs. FREQUENCY



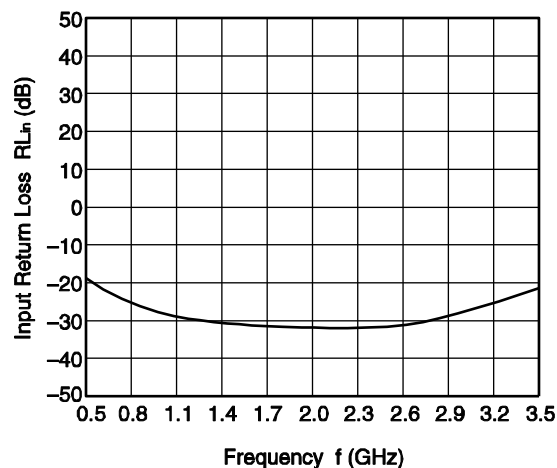
INPUT-OUTPUT2 •
ISOLATION vs. FREQUENCY



INPUT-OUTPUT1 •
INPUT RETURN LOSS vs. FREQUENCY

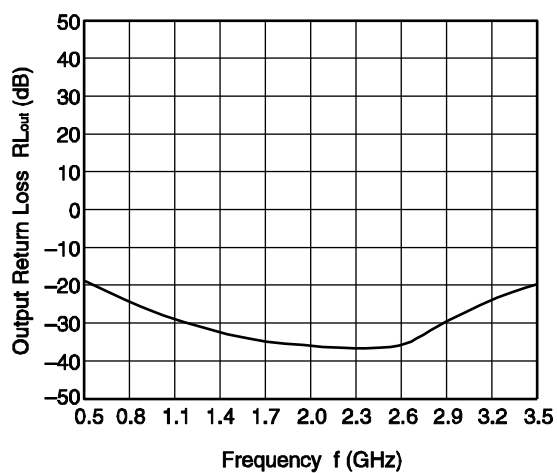


INPUT-OUTPUT2 •
INPUT RETURN LOSS vs. FREQUENCY

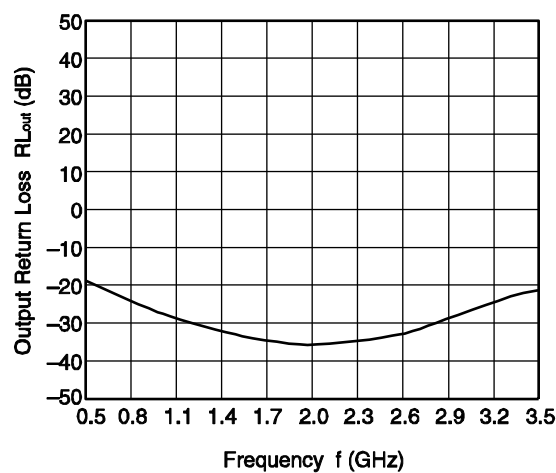


Remark The graphs indicate nominal characteristics.

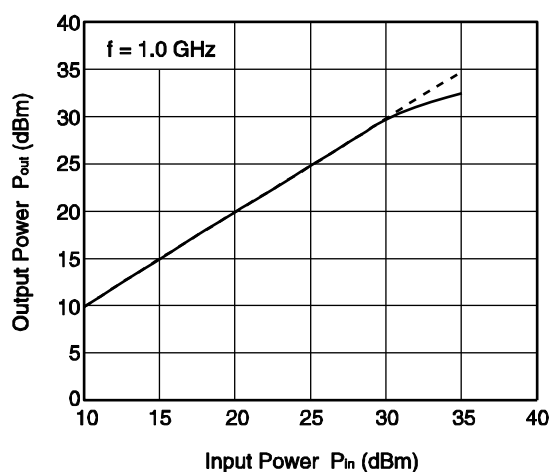
INPUT-OUTPUT1 •
OUTPUT RETURN LOSS vs. FREQUENCY



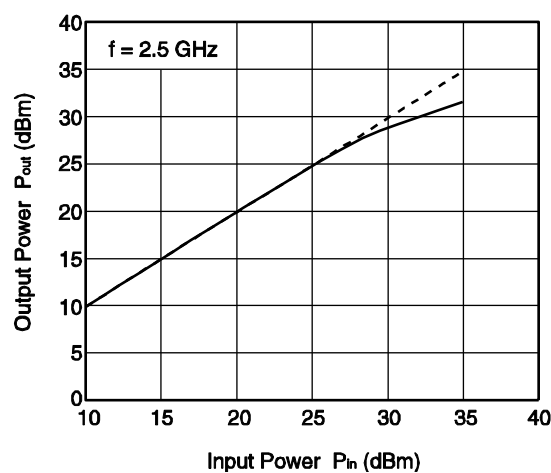
INPUT-OUTPUT2
OUTPUT RETURN LOSS vs. FREQUENCY



OUTPUT POWER vs. INPUT POWER



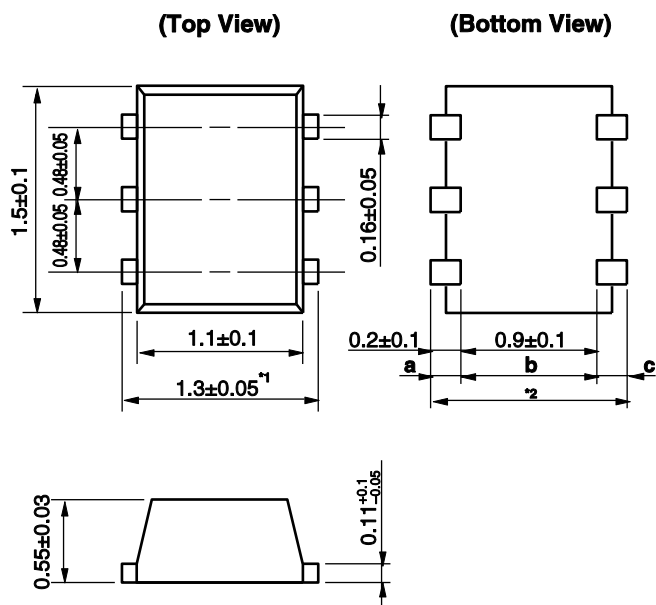
OUTPUT POWER vs. INPUT POWER



Remark The graphs indicate nominal characteristics.

<R> PACKAGE DIMENSIONS

6-PIN LEAD-LESS MINIMOLD (1511 PKG) (UNIT: mm)



Remark Dimension 1 is bigger than dimension 2 (dimension $2 = a + b + c$).

<R> **RECOMMENDED SOLDERING CONDITIONS**

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions	Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) : 260°C or below Time at peak temperature : 10 seconds or less Time at temperature of 220°C or higher : 60 seconds or less Preheating time at 120 to 180°C : 120±30 seconds Maximum number of reflow processes : 3 times Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	IR260
Wave Soldering	Peak temperature (molten solder temperature) : 260°C or below Time at peak temperature : 10 seconds or less Preheating temperature (package surface temperature) : 120°C or below Maximum number of flow processes : 1 time Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (pin temperature) : 350°C or below Soldering time (per side of device) : 3 seconds or less Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).

Caution	GaAs Products	<p>This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.</p> <ul style="list-style-type: none"> • Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below. <ol style="list-style-type: none"> 1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials. 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal. <ul style="list-style-type: none"> • Do not burn, destroy, cut, crush, or chemically dissolve the product. • Do not lick the product or in any way allow it to enter the mouth.
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